	Application No.	Applicant(s)
Notice of Allowability	10/806,378	KOMURO ET AL.
	Examiner	Art Unit
	Barbara Summons	2817
The MAILING DATE of this communication appears on the cover sheet with the correspondence address All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS. This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.		
1. This communication is responsive to		
2. The allowed claim(s) is/are <u>1-6</u> .		
3. The drawings filed on 23 March 2004 are accepted by the Examiner.		
 4.		
Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application. THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.		
5. A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.		
 6. CORRECTED DRAWINGS (as "replacement sheets") must be submitted. (a) including changes required by the Notice of Draftsperson's Patent Drawing Review (PTO-948) attached 1) hereto or 2) to Paper No./Mail Date (b) including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d). 7. DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the 		
attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL.		
 Attachment(s) 1. ☑ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☑ Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date 7/15/04 4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material 	6. ☐ Interview Summary Paper No./Mail Dat 98), 7. ☐ Examiner's Amendn	e

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REASONS FOR ALLOWANCE

1. The following is an examiner's statement of reasons for allowance:

The prior art of record does not disclose or fairly suggest an electronic component comprising a piezoelectric resonator mounted by face down bonding so as to have a "die shear strength" meeting the recited equation relating to the number and diameter of the "projecting portions" (a.k.a. bumps or balls). Although the prior art of record does generally discuss shear strength and the diameter of bumps after bonding (see discussion of the cited art below), the prior art does not disclose the number of bumps and the relation to diameter and die shear strength.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

2. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

Uchikoba U.S. 6,698,084 discloses a piezoelectric resonator SAW chip that is flip chip gold/gold bump mounted (see col. 7, lines 56-62) and discusses the chip shear strength based on the diameter of a gold wire forming the bumps (see Table 2), but does not discuss the diameter of the bumps after mounting or the number of bumps.

Uchikoba U.S. 6,628,178 is a similar SAW chip device and discloses the diameter of the bumps after bonding (see col. 8, lines 49-50).

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Takata et al. U.S. 6,557,225 discloses a SAW chip face down mounted by three bumps (see cover figure) and discusses the die shear strength (see Fig. 3), but does not discuss the diameter of the bumps.

Takeishi et al. U.S. 6,778,038 and Ella et al. U.S. 6,509,813 and Bradley et al. U.S. 6,550,664 and Ella U.S. 5,872,493 are each generic teachings of mounting thin film bulk acoustic wave resonator filters via flip-chip/bump bonding techniques. Some of these also disclose duplexers.

Chiyoma et al. JP 10-107078 discloses a method to improve shear strength of electronic components that are bump bonded.

3. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Barbara Summons whose telephone number is (571) 272-1771. The examiner can normally be reached on M-Th, M-Fr.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bob Pascal can be reached on (571) 271-1769. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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June 5, 2005

BARBARA SUMMONS PRIMARY EXAMINER

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